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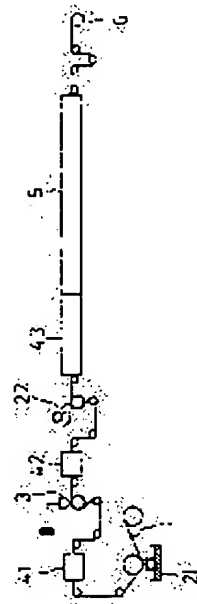
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## (54) PREPARATION OF BOARD FOR FLEXIBLE PRINTED WIRING

### (57)Abstract:

**PURPOSE:** To continuously prepare a board for flexible printed wiring by simple operation using a relatively simple apparatus by performing coating and drying/ curing over two or more times using a plurality of polyimide precursor resin solutions.

**CONSTITUTION:** Solution prepared by dissolving two or more polyimide precursor resins in a solvent such as dimethylacetamide are applied to a conductor 1 composed of a metal foil such as a copper foil using a gravure coater 21, a die coater 3 and a reverse roll coater 21 so as to form the first layer of polyamic acid A, the second layer of polyamic acid B and the third layer of polyamic acid A. The first and second layers are dried by dryers 41, 42 and the third layer is dried and cured by a dryer 43 and a curing device 5. By this method, a board for flexible printed wiring generating no curling and excellent in heat resistance and adhesiveness is prepared by a relatively simple apparatus and operation.



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